

Initial Product/Process Change Notification

Document #:IPCN25332X Issue Date:28 Sep 2023

Title of Change:	Galvanic Isolation Proc	Galvanic Isolation Process 2nd source from "Gresham" to "Gresham or Aizu"		
Proposed First Ship date:	16 Oct 2024 or earlier if approved by customer			
Contact Information:	Contact your local onse	Contact your local onsemi Sales Office or <u>Izel.Rodriguez@onsemi.com</u>		
PCN Samples Contact:	Sample requests are to PCN or Final PCN, for the Samples delivery timing	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Type of Notification:	advance notification ab change details and dev The completed qualific Change Notification (FF Change Notification (FF	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >		
Marking of Parts/ Traceability of Change:		Part marking shows assembly site and assembly date. Assembly lot (marked on reel and shipping boxes) is traceable to source wafer fab.		
Change Category:	Wafer Fab Change	Wafer Fab Change		
Change Sub-Category(s):	Manufacturing Site Add	Manufacturing Site Addition		
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Aizu, Japan		None		

Description and Purpose:

onsemi would like to notify its customers of its intent to qualify our Isolated Gate Driver technology at our onsemi Aizu, Japan wafer FAB. The qualification enables expanded capacity for this technology. All products listed in this IPCN, upon completion of qualification and the FPCN, may be dual sourced from either the current onsemi wafer FAB at onsemi Gresham, US or onsemi Aizu, Japan.

	From	То
Fab Site	onsemi, Gresham US	onsemi, Gresham US or onsemi, Aizu Japan

There is no product marking change as a result of this change.

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Qualification Plan:

QV DEVICE NAME: NCV57252DWR2G

RMS: 90740

PACKAGE: SOIC16 WB

Test	Specification	Condition	Interval
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
Early Life Failure Rate	AECQ100-008	Ta=125°C, 100 % max rated Vcc	48 hrs
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cycs
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs

Estimated date for qualification completion: 17 April 2024

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Part Number	Qualification Vehicle
NCD57252DWR2G	NCV57252DWR2G
NCD57540DWKR2G	NCV57252DWR2G

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